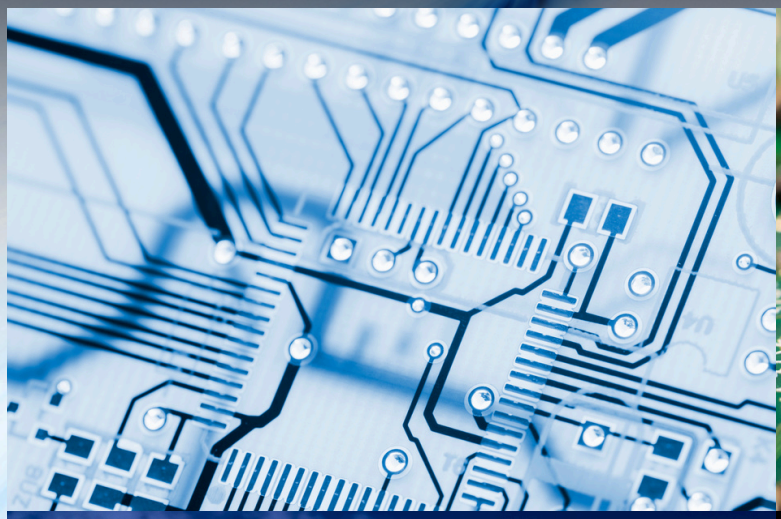
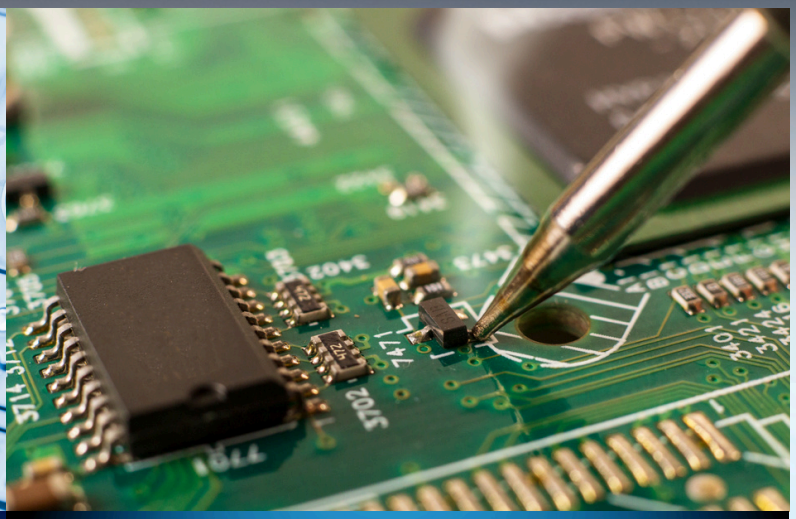
ENIGMA

DEPARTMENT OF ELECTRONICS AND COMMUNICATION

2024 VOLUME - 14 2025

BONAM VENKATA CHALAMAYYA INSTITUTE OF TECHNOLOGY & SCIENCE

Approved by AICTE, New Delhi and Affiliated by JNTU, Kakinada
Accredited by NACC, Bengaluru

AMALAPURAM

saraswati namastubhyam
varade kaamarupini
vidyaaramham karisyaami
siddhirbhavatu me sada

Late Sri Bonam Venkata Chalamayya

Founder Chairman **Bvc Group**

SECRETARY MESSAGE

SRI. BONAM KANAKAYYA

SECRETARY & CORRESPONDENT
BVC GROUP

It is a matter of great happiness to know that the students and the faculty of BVCITS are bringing out the Volume 14 of department magazine ENIGMA in the electronic format. As I understand, this association is intended to bring out the hidden literary talents in the students and teachers and also to inculcate technical and leadership skills among them. The outside world will come to know about the caliber of the students and the faculty through this medium. Keeping this in mind, I expect the contributions to this magazine to be of very high standard and quality.

CHAIR PERSON'S MESSAGE

SRI. BONAM KRISHNA SATISH

CHAIRMAN, BVC GROUP

The Magazine 'Enigma' in its electronic format invites a wider leadership in the Institute. The role of the teacher is to nurture the skills and talents of the students as a facilitators. This Magazine is going to showcase the strength of this department. Let this be a forum to exhibit the potential of teachers and students with their literary skills and innovative ideas.

PRINCIPAL MESSAGE

Dr. J V G RAMA RAO

PRINCIPAL, BVCITS

Each student has his own individuality and his special skills and talents, and a good educational system helps a student to nurture his talents and overcome his shortcomings. Only by providing appropriate, all-encompassing education that will lead to the development of the all-round personality of a student equipped to face the challenges of life in all his future endeavors. I feel privileged in presenting the 13th issue of our department magazine. I would like to place on record my gratitude and heartfelt thanks to all these who have contributed to make this effort a a success.

HOD MESSAGE

Dr. T S S PHANI

HOD, ECE

It gives me immense pleasure to present this edition of the ECE Department ENIGMA Magazine, a platform that celebrates the creativity, knowledge, and achievements of our students and faculty. This magazine is a reflection of the enthusiasm and hard work of our students, showcasing their writings, project outcomes, talent, and innovative thinking. I appreciate the efforts of the editorial board, faculty coordinators, and students who have contributed to bringing out this publication successfully. I extend my best wishes to the entire ECE family. Let us continue our journey of learning, innovation, and excellence – creating a brighter and more technologically empowered future.

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

ENIGMA

2024-25

VISION, MISSION AND OBJECTIVES OF THE DEPARTMENT:

VISION:

TO BECOME A RECOGNIZED CENTRE FOR QUALITY ELECTRONICS AND COMMUNICATION ENGINEERING EDUCATION AND DEVELOP ETHICALLY SOUND, GLOBALLY COMPETENT AND SOCIALLY RESPONSIBLE ENGINEERS.

MISSION:

DM 1: TO PROVIDE LEARNER-CENTRIC ELECTRONICS AND COMMUNICATION ENGINEERING EDUCATION TO OVERCOME THE PROFESSIONAL CHALLENGES.

DM 2: TO PURSUE RESEARCH AND NEW TECHNOLOGIES IN ELECTRONICS & COMMUNICATION ENGINEERING AND RELATED DISCIPLINES TO SERVE THE SOCIETY, INDUSTRY, GOVERNMENT AND SCIENTIFIC COMMUNITY NEEDS.

DM 3: TO PROMOTE ACTIVITIES FOR OVERALL DEVELOPMENT OF STAKEHOLDER WITH ETHICAL AND PROFESSIONAL RESPONSIBILITY.

PROGRAM EDUCATIONAL OBJECTIVES:

PEO 1: GRADUATES WILL EXCEL IN THEIR PROFESSIONAL CAREER AND / OR HIGHER EDUCATION BY APPLYING KNOWLEDGE OF MATHEMATICAL, SCIENTIFIC AND ELECTRONICS AND COMMUNICATION ENGINEERING.

PEO 2: GRADUATES WILL ANALYZE AND SOLVE REAL LIFE PROBLEMS, ADOPT THE MODERN ENGINEERING TOOLS TO DESIGN SYSTEMS THAT ARE ECONOMICALLY FEASIBLE AND SOCIALLY ACCEPTABLE.

PEO 3: GRADUATES WILL EXHIBIT PROFESSIONALISM, SOCIAL/ETHICAL RESPONSIBILITY AND INTER-PERSONAL SKILLS TO RELATE ENGINEERING ISSUES IN BROADER SOCIAL CONTEXT.

PEO 4: GRADUATES WILL HAVE THE ZEAL AND MOTIVATION TO GET INVOLVED IN LIFELONG LEARNING PROCESS TO BECOME INNOVATORS, ENTREPRENEURS AND LEADERS.

CHEIF EDITOR

Dr. T S S PHANI
Professor

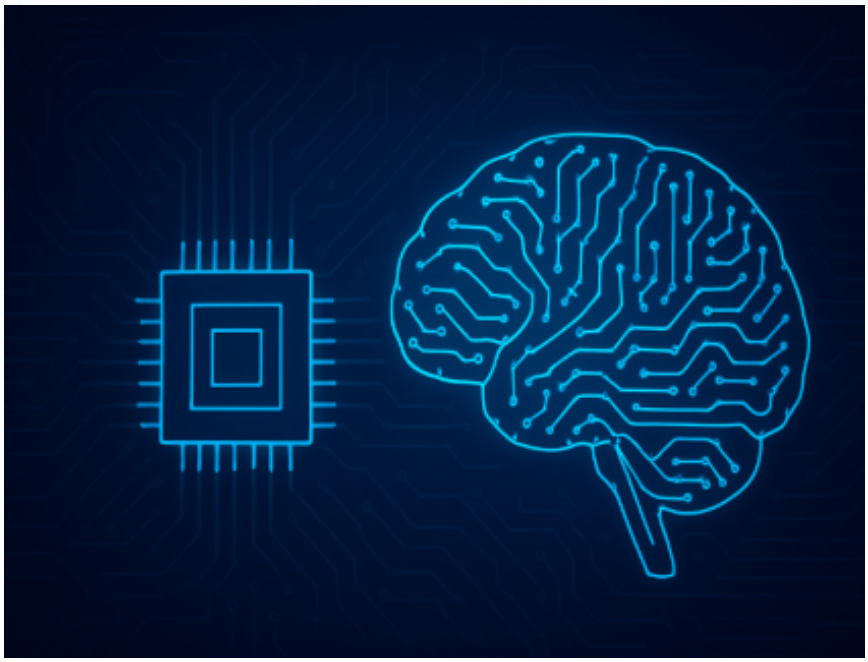
EDITORs

Ms. M S MALLIKA
Asst. Prof.

Mrs. K JYOTHIRMAI
Asst. Prof.

Neuromorphic Engineering – The Future of Brain-Inspired Computing

AKKISETTI PINAKAPANI VENKATESH
21H41A0404



In the ever-evolving world of electronics and communication engineering, Neuromorphic Engineering stands as one of the most revolutionary and futuristic fields. It combines neuroscience, computer engineering, and artificial intelligence to create electronic systems that mimic how the human brain processes information. Instead of relying on traditional computing methods, neuromorphic systems are designed to think, learn, and adapt just like biological neurons and synapses. Traditional computers follow the von Neumann architecture, where data moves back and forth between memory and the processor. This constant data transfer limits speed and increases energy consumption. Neuromorphic systems overcome this by integrating memory and computation into a single unit–just as the human brain does. This results in massive parallelism, low power consumption, and high processing

efficiency, making them ideal for applications like robotics, autonomous vehicles, edge computing, and smart sensors.

At the heart of this technology are devices like memristors and spiking neural networks (SNNs). Memristors act as artificial synapses, storing information in the form of resistance changes. SNNs process data as electrical spikes, similar to the way biological neurons communicate. These features enable neuromorphic chips to perform complex tasks–such as pattern recognition, image processing, and decision-making–with a fraction of the power required by conventional processors.

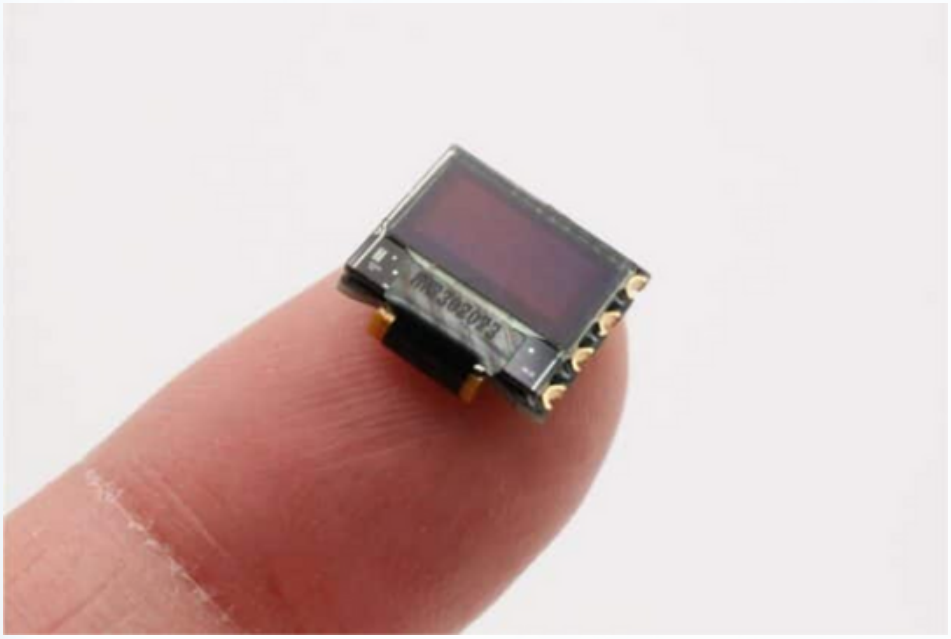
Leading companies and research institutes are developing specialized neuromorphic chips like Intel's Loihi, IBM's TrueNorth, and BrainChip's Akida. These chips represent the next step in hardware-level artificial intelligence, where machines not only process information but also adapt and learn from their experiences in real time.

However, despite these breakthroughs, neuromorphic engineering is still in its developmental stage. Researchers face challenges in scaling up hardware, reducing noise, and bridging the gap between biological models and practical engineering systems. Yet, the potential impact is immense–neuromorphic technologies could reshape the future of computing, leading to energy-efficient, self-learning, and intelligent electronic systems.

In essence, Neuromorphic Engineering is the fusion of biology and technology, paving the way for artificial systems that truly emulate the intelligence of the human brain. As this field continues to grow, it promises to revolutionize not only electronics and communication but also the very foundation of how machines perceive and respond to the world.

The Ultra-Compact Interface: World's Smallest OLED for Portable Projects

PILLA NAGA ADINARAYANA
22H41A0444



The challenge of integrating a functional display into truly miniature or wearable projects has long been a frustration for makers, engineers, and hobbyists. Traditional screens are often too bulky, forcing a compromise on either design size or usability. Questwise Ventures has tackled this head-on with the introduction of a new OLED screen, providing a powerful display solution in an incredibly small footprint.

Miniaturization Without Compromise

Measuring just a few millimeters across, this screen is approximately 20% smaller than its predecessor. Its design is a masterclass in space-saving engineering, critical for projects where every millimeter counts.

Key to this compact design are passives and castellated pads. The use of components—some of the smallest standardized resistors and capacitors—minimizes the module's overall

physical size without sacrificing performance. Furthermore, the castellated pads allow the module to be easily mounted flat onto a PCB, acting as a direct sub-assembly rather than requiring a bulky connector, thereby saving significant vertical space.

Key Applications in Embedded Systems

The small size and efficiency of this OLED make it ideal for numerous applications across Electrical and Computer Engineering (ECE) disciplines:

- Wearable Devices: For next-generation smartwatches, fitness trackers, or augmented reality glasses, the screen can display essential data like notifications, time, or biometric health metrics, all while keeping the device light and compact.
- Pocket-Sized Gadgets: Developers can use it to create pocket-sized gaming consoles for retro interfaces, showing scores, levels, or character stats.
- IoT & Monitoring: For IoT developers, the screen serves as a clean, low-power interface for monitoring and controlling connected devices. It can display real-time sensor readings, temperature, humidity, energy usage, or system status without needing a dedicated external console.
- Portable DIY Instruments: The screen is perfect for portable DIY instruments such as custom multimeters, environmental sensors, or basic oscilloscopes, clearly displaying readings, waveforms, or calibration information in the field.

The Interface Solution

For a complete user interface in a highly constrained space, the OLED screen can be effectively paired with a rotary encoder. This combination creates a simple yet powerful display and input solution for navigating menus, setting parameters, or adjusting instrument values.

The Ultra-Compact Interface: World's Smallest OLED for Portable Projects

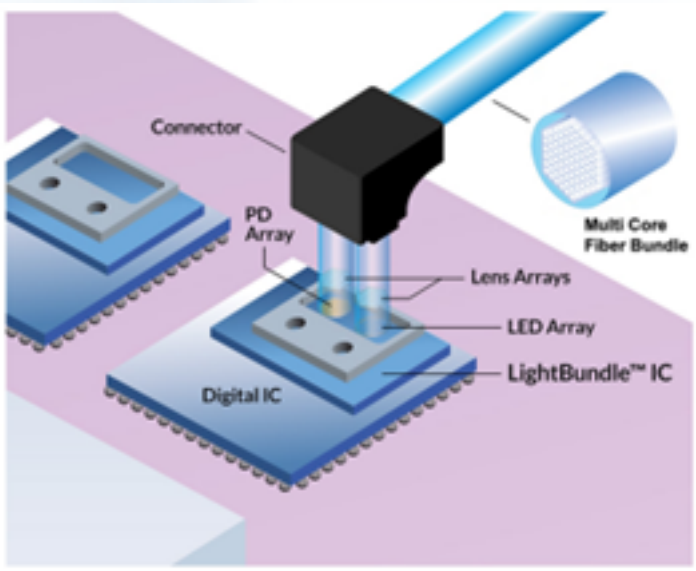
The OLED screen empowers engineers, developers, and artists to maintain strict size constraints without sacrificing the functionality of an integrated display, truly allowing creators to keep their projects small and functional.

Smaller Chip Connections For Next-Gen Data Centers

DONTABHAKTUNI VENKATA SURYA DEEPAK
22H41A0416

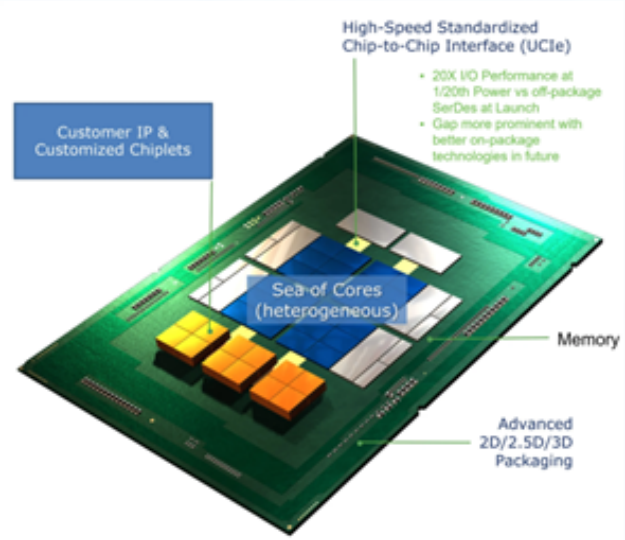
Data centers and AI chips are hitting limits in speed and efficiency. Can a 64 Gbps bi-directional interface change performance, cut power, and reduce chip size?

Data centers and chip designers face a challenge. They need to move more data at higher speeds while keeping power use and chip area in check. As workloads grow for AI and other compute applications, traditional interconnects are hitting limits in bandwidth, efficiency, and reliability.

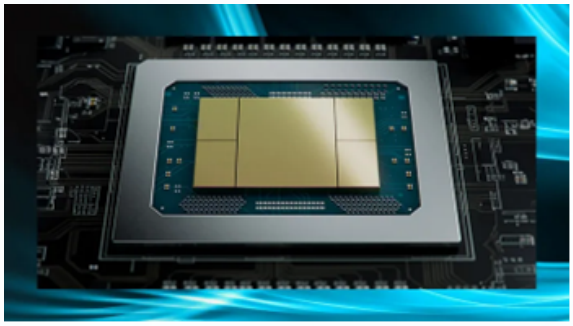


Marvell 64 Gbps Bi Directional Die to Die D2D Interface has been developed to address this. It is built on a 2nm process node and also available in 3nm. It gives next generation XPUs a way to connect compute dies. Each wire in the interface can carry 32 Gbps of two-way data, helping designers push performance without the penalty of higher energy use or larger silicon area. The technology delivers over 30 Tbps per millimeter of bandwidth density, more than three times that of UCIe at comparable speeds. Its design reduces compute die area by up to 85 percent versus conventional interconnects, while adaptive power management lowers interface power use by up to 75 percent in normal operation and 42 percent under peak loads.

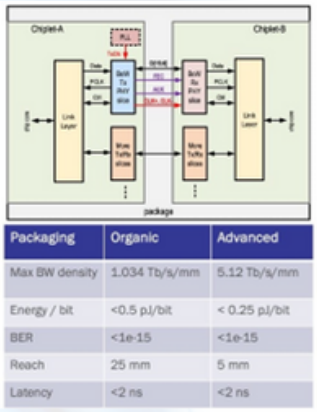
Smaller Chip Connections For Next-Gen Data Centers



Marvell has built in reliability features such as redundant lanes and automatic lane repair to reduce bit errors and improve yields. To make adoption easier, the company offers not just the D2D PHY but a complete stack including the application bridge, link layers, and physical interconnect. This gives chip designers a platform for building the next wave of XPUs.



This product is aimed at chip designers and semiconductor companies working on next generation XPUs and processors. It is useful for teams designing AI accelerators, data center processors, and other compute systems that need faster die-to-die communication while minimizing power use and chip area.



Packaging	Organic	Advanced
Max BW density	1.034 Tb/s/mm	5.12 Tb/s/mm
Energy / bit	<0.5 pJ/bit	< 0.25 pJ/bit
BER	<1e-15	<1e-15
Reach	25 mm	5 mm
Latency	<2 ns	<2 ns

"The 64 Gbps bi-directional D2D interface IP marks an industry first and reflects our commitment to pioneering technologies that enhance performance while reducing total cost of ownership for next-generation AI devices," said Will Chu, senior vice president of Custom Cloud Solutions at Marvell. "D2D interfaces–which form the backbone of the communications networks linking silicon die within the same device–are fundamental to increasing the performance and efficiency of data center semiconductors and especially the rapidly growing custom computing segment," said Baron Fung, Senior Director of Research at Dell'Oro.

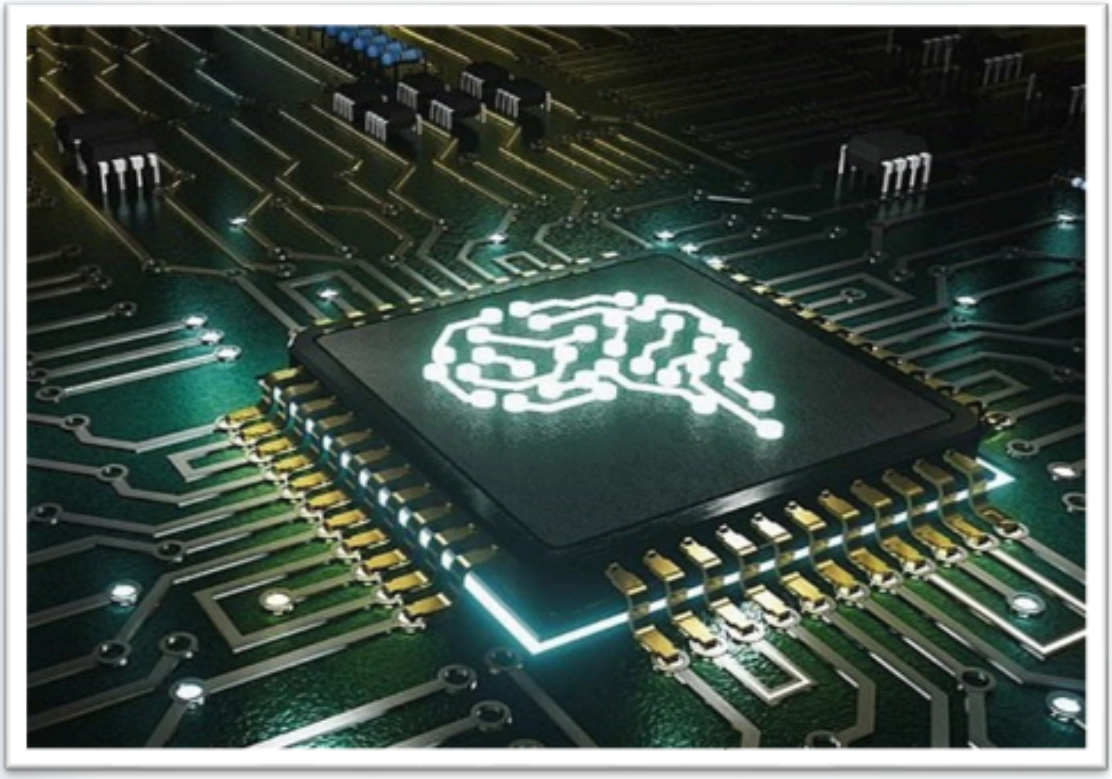
Brain Chip Technology: The Future of Human-Machine Interaction

Bhogisetti Adithya
22H41A0410

A brain chip, also known as a Brain-Computer Interface (BCI), is a device that connects the human brain directly with external electronic systems. This groundbreaking technology enables communication between neurons and machines, allowing thought-controlled actions such as moving prosthetic limbs, typing on a computer, or even restoring lost senses. Recent advancements have revolutionized this field. Elon Musk's Neuralink has successfully implanted its "Link" chip in human subjects, enabling paralyzed individuals to control digital devices. Similarly, China's NeuCyber NeuroTech has developed a wireless semi-invasive chip named "Beinao No.1," showing promise for restoring movement in paralyzed patients. Researchers at EPFL, Switzerland, created a miniature chip that converts thoughts into text, while India's IISc introduced.

"Brain-on-a-Chip" technology that mimics human neurons for smarter, energy-efficient computing. Applications of brain chips extend to medical therapies, helping patients with neurological conditions such as ALS, spinal injuries, or stroke. They also enable assistive communication for those who cannot speak or move. Beyond medicine, these chips could enhance memory, cognition, and human-AI integration. However, several challenges remain—ensuring signal stability, biocompatibility, power efficiency, and data security. Ethical issues like privacy,

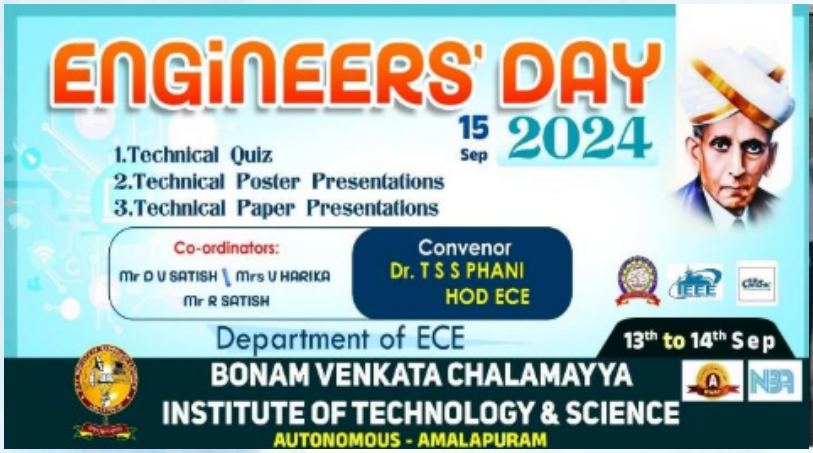
consent, and equitable access must also be addressed to prevent misuse of neural data. In the future, brain chips may redefine how humans interact with technology. As AI advances, merging human cognition with intelligent machines could open new frontiers in science, medicine, and society–ushering in an era of true human-technology symbiosis.



FRESHER'S DAY

Fresher's day is a platform where the junior's display their hidden talents. The most important thing is to enjoy moments of togetherness and make them feel good about being a part of our college. It is accompanied by so many exciting events and programs like ramp walk, traditional, fusion and modern dances and splendid decoration.

ENGINEER'S DAY



This day commemorates the birth of the first engineer Sir Mokshagundam Visvesvaraya, also known as the Father of Engineering. A nation growth depends on its engineers as they are at the forefront of innovation, problem solving and technological advancement. The engineer's day celebrations encompassed a variety of technical events, including paper presentation, poster presentation and quiz, all aimed to inspiring engineer's and emphasizing the significance of engineering.

GANESH CHATURTHI

Ganesh chaturthi is a 10-day long celebrations. Ganesha's large head represents wisdom and intellect, making him the ideal deity for students to seek blessings. Lord ganesh always teaches us to respect everyone and be humble to everyone. The college organized a vibrant celebrations where students and faculty came together to honor Lord Ganesha, through traditional rituals.

FAREWELL PARTY

The IIIrd year students arranged farewell party to final year students on congratulating seniors for their new heights to achieve more excellence with your future.

STUDENT PLACEMENT LIST

S.NO	Regdno	Name of the student	Company	Package
1	216M1A04B6	VegiSindhuSriSaiMani	LOGSKIMSOLUTIONS PVTLTD	2.07LPA
2	21H41A0401	Achantajagadeeswari	SCHNEIDERELECTRICINDIAPVTLTD	2.07LPA
3	21H41A0402	AdabalaHLKSujitha	SCHNEIDERELECTRICINDIAPVTLTD	2.07LPA
4	21H41A0403	AdapaPrameela	SCHNEIDERELECTRICINDIAPVTLTD	2.07LPA
5	21H41A0404	AKKISETTIPINAKAPANIVENKATESH	EFFTRONICS	3.36LPA
6	21h41a0406	BorsuVanitha	ZFCommercialVehicleControlSystemsIndi	2.04LPA
7	21H41A0407	ChinnamManeesha	SCHNEIDERELECTRICINDIAPVTLTD	2.07LPA
8	21H41A0408	CHITIKELASAIKUMAR	ZFCommercialVehicleControlSystemsIndi	2.04LPA
9	21h41a0409	ChittimenuVeeraManikanta	LOGSKIMSOLUTIONS PVTLTD	2.07LPA
10	21H41A0412	DANGETIYAJNESWARI	SCHNEIDERELECTRICINDIAPVTLTD	2.07LPA
11	21H41A0414	DukkipatiTejaswi	LOGSKIMSOLUTIONS PVTLTD	2.07LPA
12	21H41A0415	DunaboyinaRavindra	ZFCommercialVehicleControlSystemsIndi	2.04LPA
13	21H41A0417	GanesnaLakshmiAnu sri	SCHNEIDERELECTRICINDIAPVTLTD	2.07LPA
14	21H41A0418	GOLLA SANDHYA	SCHNEIDERELECTRICINDIAPVTLTD	2.07LPA
15	21H41A0419	GUDDATIESWARISRISAISUJITA	TALENT-TREKE-LEARNINGPVTLTD	4.00-6.00 LPA
16	21H41A0420	Akshay	ZFCommercialVehicleControlSystemsIndi	2.04LPA

17	21H41A0421	JAKKAMPUDI SUSHMITHA	SKILL INTERN	4.20-5.20 LPA
18	21h41a0422	Nagesh Jakkavarapu	PENTAGONSPACE	2.24LPA-4.50 LPA
19	21H41A0424	Jithukasiddhardha	ZFCommercialVehicleControlSystemsIndi	2.04LPA
20	21h41a0425	Jogipriyanka	LOGSKIMSOLUTIONS PVTLTD	2.07LPA
21	21h41a0426	KALLA SRUTHI	NXTSYNCPVTLTD	4.50LPA
22	21H41A0427	KANCHUSTAMBHAMSAI PAVANSEKHAR	SEOAKINNOVATIONS PRIVATELIMITED	5.00-7.00 LPA
23	21H41A0428	Sireeshakatadi	ZFCommercialVehicleControlSystemsIndi	2.04LPA
24	21H41A0429	Devikaketha	LOGSKIMSOLUTIONS PVTLTD	2.07LPA
25	21H41A0431	Janaki	ZFCommercialVehicleControlSystemsIndi	2.04LPA
26	21H41A0432	KotipalliLakshmiPrasanna	ZFCommercialVehicleControlSystemsIndi	2.04LPA
27	21H41A0433	KOTIPALLISAIKRISHNA	LOGSKIMSOLUTIONS PVTLTD	2.07LPA
28	21H41A0435	KURACHALAKSHMIDURGAPREMASINDHUJA	HAPPIESMINDS	4.20LPA
29	21H41A0436	MARELLAMOUNIKA	SKILL INTERN	4.20-5.20 LPA
30	21H41A0437	GaneshMedida	ZFCommercialVehicleControlSystemsIndi	2.04LPA
31	21H41A0439	MohammadAyeshaJabeen	LOGSKIMSOLUTIONS PVTLTD	2.07LPA
32	21H41A0442	NagallaNagaMalleswari	SCHNEIDERELECTRICINDIAPVTLTD	2.07LPA
33	21H41A0443	NalamSaiEswar	LOGSKIMSOLUTIONS PVTLTD	2.07LPA
34	21h41a0444	NallaNavyaSaiSriLakshmi	PENTAGONSPACE	2.24LPA-4.50 LPA
35	21H41A0445	NandhikaLakshmiLavanya	SCHNEIDERELECTRICINDIAPVTLTD	2.07LPA
36	21H41A0446	NandyalaRatnakumari	SCHNEIDERELECTRICINDIAPVTLTD	2.07LPA

37	21H41A0447	NIMMAKAYALASRIRAMA RATNAPRASANTHI	SCHNEIDERELECTRI CINDIAPVTLTD	2.07LPA
38	21H41A0448	PANTHANISIRISHA	SCHNEIDERELECTRI CINDIAPVTLTD	2.07LPA
39	21H41A0450	Pilli.Jnaneswari	SCHNEIDERELECTRI CINDIAPVTLTD	2.07LPA
40	21H41A0451	PINDINAGADURGASAIVI JAYALAKSHMI	SCHNEIDERELECTRI CINDIAPVTLTD	2.07LPA
41	21H41A0452	POLISETTICHAYARAMAL AKSHMI	SCHNEIDERELECTRI CINDIAPVTLTD	2.07LPA
42	21H41A0453	PURUSHOTHAMLAVAN YA	SCHNEIDERELECTRIC INDIAPVTLTD	2.07LPA
43	21H41A0454	PURUSHOTTAMPOORN ACHANDINI	SCHNEIDERELECTRIC INDIAPVTLTD	2.07LPA
44	21H41A0457	RUDRANAGASATYADUR GADEVIKA	TALENT-TREKE-LEARNINGPVTLTD	4.00-6.00 LPA
45	21H41A0458	SELADIMPLESRIDEVI	SCHNEIDERELECTRIC INDIAPVTLTD	2.07LPA
46	21H41A0460	SurampudiSatyaNagaD urgaPrasoona	SCHNEIDERELECTRIC INDIAPVTLTD	2.07LPA
47	21H41A0466	YandraSuguna	SCHNEIDERELECTRIC INDIAPVTLTD	2.07LPA
48	21H41A0467	ACHANTAGEETHASARA NYA	TALENT-TREKE-LEARNINGPVTLTD	4.00-6.00 LPA
49	21H41A0468	ADAPACHAITANYASUR YALAKSHMI	QSPIDERS	3.00-4.50 LPA
50	21H41A0474	CHIKKAMSOWJANYARA MAMUTYAMANI	CAPGEMINI	4.00LPA
51	21h41a0478	DONGANAGASAIRAMYA SREE	TALENT-TREKE-LEARNINGPVTLTD	4.00-6.00 LPA
52	21H41A0479	DUNNALABHAGYA SRI	INFOSYS	3.60LPA
53	21H41A0480	EllimilliMeghana	SCHNEIDERELECTRIC INDIAPVTLTD	2.07LPA
54	21H41A0482	GALIDEVARASRI NEYYA	TALENT-TREKE-LEARNINGPVTLTD	4.00-6.00 LPA
55	21H41A0483	GANDHAMSRIPRIYA	SKILL INTERN	4.20-5.20 LPA

56	21H41A0486	KAMADIBHAVANIHARIKA	SCHNEIDERELECTRIC INDIAPVTLTD	2.07LPA
57	21H41A0487	KarriSravani	CAPGEMINI	7.50LPA
58	21H41A0488	KOPPINEDILAKSHMIPRASANNA	NXTSYNCPVTLTD	4.50LPA
59	21H41A0489	KoppisettiRajyaLakshmi Rakshitha	TALENT-TREKE-LEARNINGPVTLTD	4.00-6.00 LPA
60	21H41A0491	KoppisettiSurya	QSPIDERS	3.00-4.50 LPA
61	21H41A0496	KUSUNURISANTOSHKUMAR	HCL	6.00LPA
62	21H41A0497	LAKKIMSETTISWATHI	SCHNEIDERELECTRIC INDIAPVTLTD	2.07LPA
63	21H41A0498	LINGOLUPOOJARAKSHITHA	SEOAKINNOVATIONS PRIVATELIMITED	5.00-7.00 LPA
64	21h41a04a3	MANEMALLIKARAMYA	PENTAGONSPACE	2.24LPA-4.50 LPA
65	21H41A04A6	MedepalliPavani	SCHNEIDERELECTRIC INDIAPVTLTD	2.07LPA
66	21H41A04A7	MedicharlaDurgaLakshmi	SCHNEIDERELECTRIC INDIAPVTLTD	2.07LPA
67	21H41A04A8	MEKALAANUNAGAVENKATALAKSHMI	SKILL INTERN	4.20-5.20 LPA
68	21H41A04B1	NAMANAGOWRIDEVI	SEOAKINNOVATIONS PRIVATELIMITED	5.00-7.00 LPA
69	21H41A04B3	OduriSriNagaDevi	TECHWAVEINFOTECH PRIVATELIMITED	2.20LPA
70	21H41A04B5	PRASANNADEVIKANDREGULA	COGNIZANT	5.40LPA
71	21H41A04B6	PulidindiTasli	COGNIZANT	4.00LPA
72	21H41A04C1	SAVARAPUSRINIJA	SCHNEIDERELECTRIC INDIAPVTLTD	2.07LPA
73	21H41A04C3	Talabathulavindhyamrutha	SCHNEIDERELECTRIC INDIAPVTLTD	2.07LPA
74	21H41A04C4	TELAGANIPRAVEENARAMANAGA SRI	SCHNEIDERELECTRIC INDIAPVTLTD	2.07LPA
75	22H45A0402	DARAPURAHUL	EFFTRONICS	3.36LPA

76	22H45A0403	GARAGASRAVANREVANTH	EFFTRONICS	3.36LPA
77	22H45A0409	MUDUMBAHANUMASADHANA	PEOPLETECHGROUP	2.24LPA
78	22H45A0410	MUTTABATHULASUVIJNA	SCHNEIDERELECTRICINDIAPVTLTD	2.07LPA
79	22H45A0411	PemmadiAdiLakshmi	SCHNEIDERELECTRICINDIAPVTLTD	2.07LPA
80	22H45A0412	SAMSANINAGAMOUNIKA	SCHNEIDERELECTRICINDIAPVTLTD	2.07LPA

EDITORIAL BOARD COMMITTEE MEMBERS

CHIEF EDITOR

Dr. T S S PHANI, Professor

EDITORs

Ms. M S MALLIKA, Asst. Prof.

Mrs. K JYOTHIRMAI, Asst. Prof.

STUDENT MEMBERS

21H41A0404

22H41A0416

23H41A0415